TOSHIBA
IWATE TOSHIBA ELECTRONICS CO., LTD.
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JUNE 19, 2015
PCN#:15CN-005

PROCESS CHANGE NOTIFICATION

Dear Customers,

We thank you for your support and corporation.
This is to inform you that we will please suggest Wafer diameter, Wafer production place and PKG materials, an assembling base change. If you have any questions, please feel free to contact us.
We would appreciate your support and cooperation.

1. Affected product

- TB6819AFG

2. Contents of change point

			<Current> **TB6819AFG(PSD,EL)**	<New> **TB6819AFG(Z,EL)**
Wafer	Man		(Oita)	(Iwate)
	Inch		6inch	8inch
	Method	Flat formation of interlayer dielectric	Melt / resist etch back	CMP
		Multilayer formation	Cont：Through hole Flat formation of Via：EB	Cont：W-Plug Flat formation of Via：CMP
	Wafer Material	Wafer	8 inch wafer material is used, but purchase standard is same.	
		AL wiring	Al-Si-Cu	Al-Cu (8 inch in existence)
		interlayer	Interlayer is formed by using material of 8 inch existing products.	
Assembly	Man		The worker of J-Device	The worker of AOI Electronics
	Assembly Material	Lead frame	Iron alloy	Copper alloy
		Die-attach paste	Ag Paste (Type-A)	Ag Paste (Type-B)
		Bonding Wire	Au	Pd Cu
		Mold resin	Epoxy (Type-A)	Epoxy (Type-B)
		Plating	Sn-Ag	Pure Sn
	Package type		J-Device type	AOI Electronics type JEDEC type
	Per inner carton		2000 pcs/Reel	4000 pcs/Reel
	Material	Tape type	J-Device type	AOI Electronics type
		Reel	J-Device type	AOI Electronics type
		Carton	Carton (Type-A)	Carton (Type-A)

(Oita) : Toshiba Corp. Oita factory
(Iwate) : Iwate Toshiba electronics Co., Ltd.

3. Reason of the change

- Steady supply.

4. Schedule

-Change plan: Nov, 2015
- We will be shipped Iwate products to you as soon as you has been approved this inform.

YOUR UNDERSTANDING WILL BE HIGHLY APPRECIATED.
SINCERELY YOURS,

H. Watanabe

HIROTAKA WATANABE
MANAGER
QUALITY ASSURANCE SECTION
IWATE TOSHIBA ELECTRONICS CO., LTD.